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Jameco Part Number 894809



Data sheet acquired from Harris Semiconductor SCHS056D – Revised August 2003

CMOS OR Gates

High-Voltage Types (20-Volt Rating)

Quad 2-Input OR Gate CD4072B Dual 4-Input OR CD4075B Triple 3-Input OR

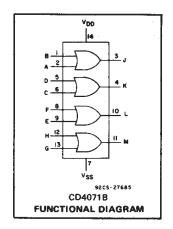
■ CD4071B, CD4072B, and CD4075B OR gates provide the system designer with direct implementation of the positive-logic OR function and supplement the existing family of CMOS gates.

The CD4071B, CD4072B, and CD4075B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

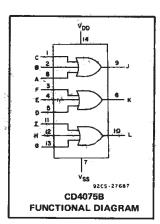
CD4071B, CD4072B, CD4075B Types

Features:

- Medium-Speed Operation-tp $_{LH}$, t_{PHL} = 60 ns (typ.) at V_{DD} = 10 V
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Standardized, symmetrical output characteristics
- Noise margin (over full package temperature range)
 - 1 V at V_{DD} = 5 V 2 V at VDD = 10 V
 - 2.5 V at VDD = 15 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



9205-27686 CD4072B **FUNCTIONAL DIAGRAM**



RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIN	UNITS	
	MIN.	MAX.	
Supply-Voltage Range (For TA = Full Package-Temperature Range)	3	18	٧

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER-	CONDITIONS			LIMI	TS AT	INDICAT	TED TE	MPERATURES (°C)				
ISTIC	Vo	VIN	VDD						+25		UNITS	
	(V)	(V)	(V)	-55	40	+85	+125	Min.	Тур.	Max.		
Quiescent Device	_	0,5	5	0.25	0.25	7.5	7.5	_	0.01	0.25		
Current,		0,10	10	0.5	0,5	15	15	-	0.01	0,5	٠ ا	
IDD Max.	-	0,15	15	1	1	30	30	-	0.01	1	μΑ	
	-	0,20	20	5	5	150	150	-	0.02	5		
Output Low	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	-		
(Sink) Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-		
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	_		
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	_	mA	
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-		
Current, IOH Min.	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-		
TOH WIIII.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-		
Output Voltage:	_	0,5	5		0.05				0	0.05		
Low-Level, VOI Max.	_	0,10	10		0	.05		-	0	0.05		
VUL 11110X.	_	0,15	15		0	.05		_	0	0.05		
Output Voltage:	_	0,5	5	4.95 4.95					5	-	·	
High-Level, VOH Min.	_	0,10	10		9	.95		9.95	10	-		
AOH MIII.	_	0,15	15		14	.95		14.95	15	-		
Input Low	0.5, 4.5		. 5		1	.5		_	Γ –	1.5	v	
Voltage, VII Max.	1, 9	_	10			3		-	_	3		
AIT Max.	1.5,13.5	+	15			4		_	_	4		
Input High Voltage,	4.5	1	5		3	3.5		3.5				
	9	, , ,	10			7		7		_		
VIH Min.	13.5		15	5 11 11 -					— <u>,</u>	_		
Input Current IJN Max.	i i	0,18	18	±0.1	±0.1	±1	±1	<u>-</u> :	±10 ⁻⁵	±0.1	μА	

CD4071B, CD4072B, CD4075B Types

MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (V _{DD})	
Voltages referenced to V _{SS} Terminal)0.5V to	
INPUT VOLTAGE RANGE, ALL INPUTS0.5V to VDD	+0.5V
DC INPUT CURRENT, ANY ONE INPUT±	:10mA
POWER DISSIPATION PER PACKAGE (PD):	
For T _A = -55°C to +190°C 50	WmOC
For T _A = +100°C to +125°C	Wm00
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	00mW
OPERATING-TEMPERATURE RANGE (TA)55°C to +	125°C
STORAGE TEMPERATURE RANGE (Tstg)65°C to +	
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s max	265°C

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C, Input t_r, t_f = 20 ns, and C_L = 50 pF, R_L = 200 $\,k\Omega$

CHARACTERISTIC	TEST COND	TIONS	ALL LIN	UNITS	
		V _{DD} VOLTS	TYP.	MAX.	
Propagation Delay Time, tpHL, tpLH		5 10 15	125 60 45	250 120 90	ns
Transition Time, ^t THL ^{, t} TLH		5 10 15	100 50 40	200 100 80	ns
Input Capacitance, C _{IN}	Any Input	1 – 1	5	7.5	pF

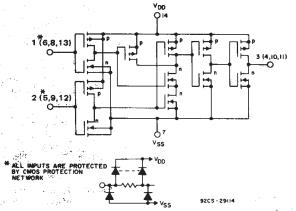


Fig. 3 - Schematic diagram for CD40718 (1 of 4 identical gates).

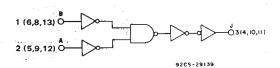


Fig. 5 -/ Logic diagram for CD4071B (1 of 4 identical gates).

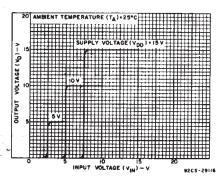


Fig. 1 — Typical voltage transfer characteristics

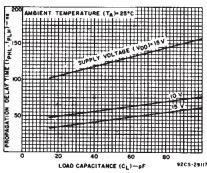


Fig. 2 — Typical propagation delay time as a function of load capacitance.

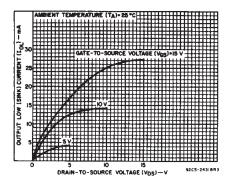


Fig. 4 — Typical output low (sink) current characteristics.

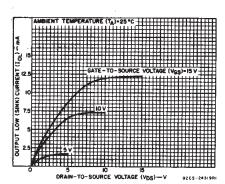
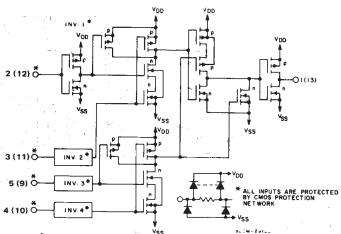


Fig. 6 — Minimum output low (sink) current characteristics.

CD4071B, CD4072B, CD4075B Types



INVERTERS 2,3 AND 4 ARE IDENTICAL TO INVERTER 1.

Fig. 7 - Schematic diagram for CD4072B (1 of 2 identical gates).

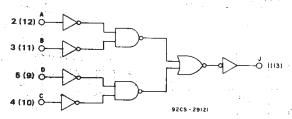


Fig. 9 - Logic diagram for CD4072B (1 of 2 identical gates).

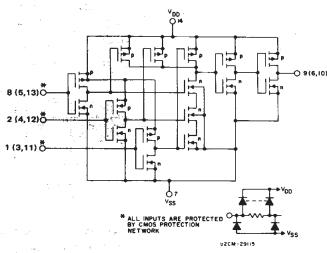


Fig. 11 - Schematic diagram for CD4075B (1 of 3 identical gates).

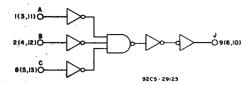


Fig. 13 - Logic diagram for CD4075B (1 of 3 identical gates).

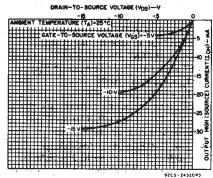


Fig. 8 — Typical output high (source) curren characteristics.

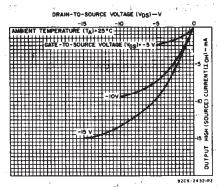


Fig. 10 – Minimum output high (source) current characteristics.

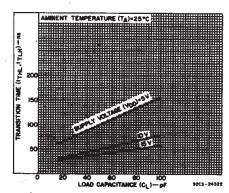


Fig. 12 - Typical transition time as a function of load capacitance.

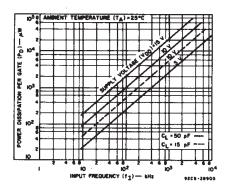
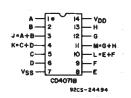
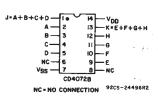


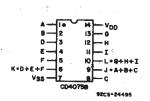
Fig. 14 — Typical dyanamic power dissipation as a function of frequency.

CD4071B, CD4072B, CD4075B Types

TERMINAL ASSIGNMENTS (TOP VIEW)







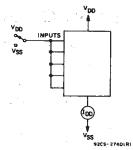


Fig. 15 - Quiescent device current test circuit.

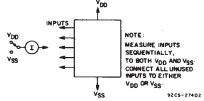


Fig. 16 - Input current test circuit.

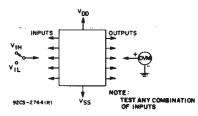
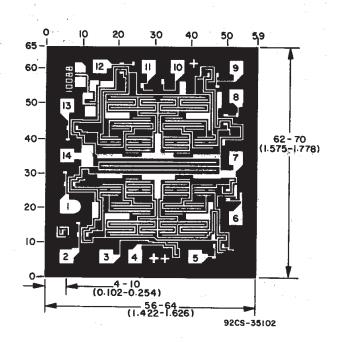
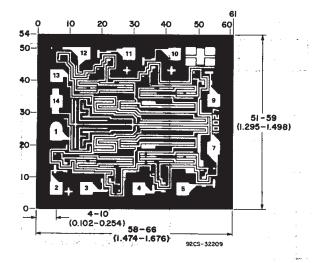


Fig. 17 - Input-voltage test circuit.

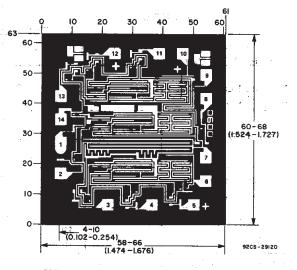
Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).



Chip dimensions and pad layout for CD4071B.



Chip dimensions and pad layout for CD4072B.



Chip dimensions and pad layout for CD4075B.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
7706002CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD4071BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4071BEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4071BF	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD4071BF3A	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD4071BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4071BPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4072BEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4072BF	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD4072BF3A	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD4072BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)		Level-1-260C-UNLIM
CD4072BM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





18-Jul-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
CD4072BNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4072BPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4075BEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4075BF	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD4075BF3A	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD4075BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4075BPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
JM38510/17101BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/17103BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

18-Jul-2006

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

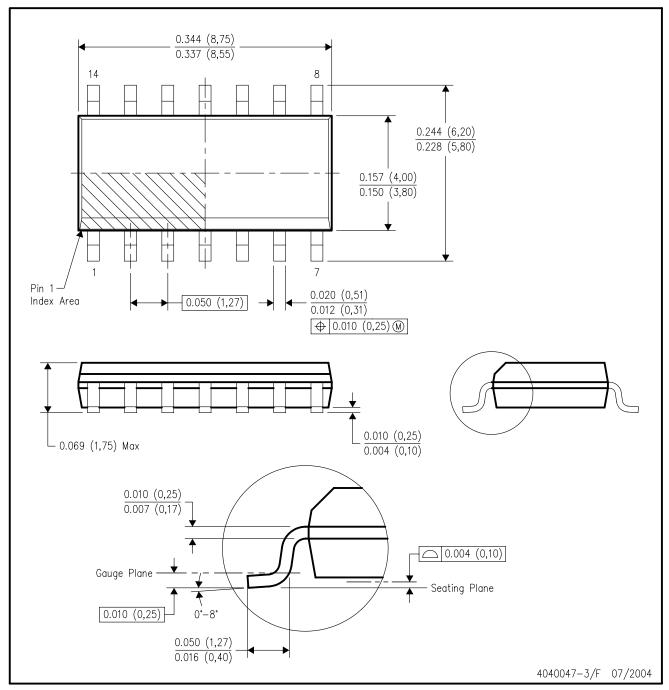


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Post Office Box 655303 Dallas, Texas 75265

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